



# Film Capacitors

## Metallized Polyester Film Capacitors (MKT)

**Series/Type: B32231**

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
see following page		2014-04-11	2014-07-15	2014-10-15

For further information please contact your nearest EPCOS sales office, which will also support you in selecting a suitable substitute. The addresses of our worldwide sales network are presented at [www.epcos.com/sales](http://www.epcos.com/sales).

© EPCOS AG 2015. Reproduction, publication and dissemination of this publication, enclosures hereto and the information contained therein without EPCOS' prior express consent is prohibited.

EPCOS AG is a TDK Group Company.

## Affected products (Ordering code)

<b>B32231C6475K000</b>	B32231S1225M500
B32231D1106J000	B32231S1225M502
B32231D1106K000	B32231S3245K501
B32231D1335K000	B32231S3686K502
B32231D1475J000	B32231S6155K501
B32231D3106K000	B32231S6225K503
B32231D3106M000	B32231S6255K504
B32231D3125K006	B32231S6845J500
B32231D3335J000	B32231S7155K500
B32231D3335K000	B32231S7155K501
B32231D3375K000	B32231S7155K502
B32231D3475K000	B32231S7505K500
B32231D3565K000	B32231S7505K501
B32231D3685K000	B32231S7505K502
B32231D3824K006	
B32231D6105K000	
B32231D6106K000	
B32231D6155K000	
B32231D6155M000	
B32231D6225K000	
B32231D8684K000	

**General purpose (wound)**
**Typical applications**

- Smoothing
- Filtering

**Climatic**

- Max. operating temperature: 100 °C
- Climatic category (IEC 60068-1): 40/100/21

**Construction**

- Dielectric: polyethylene terephthalate (polyester, PET)
- Flat winding
- Insulating sleeve
- Face ends sealed with epoxy resin

**Features**

- RoHS-compatible

**Terminals**

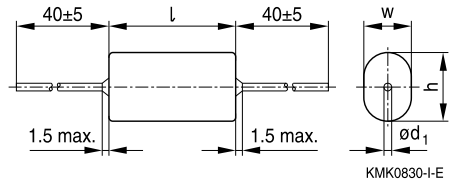
- Central axial wire leads, lead-free tinned

**Marking**

Manufacturer, series number, rated capacitance (coded), capacitance tolerance (code letter), rated DC voltage, date of manufacture (coded)

**Delivery mode**

Bulk (untaped)

**Dimensional drawing**


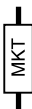
Dimensions in mm

Width $w_{max}$	≤6.0	>6.0 ... 13.0
Lead diameter $d_1$	0.6	0.8

When bending leads take care to leave a clearance of 1 mm to the capacitor body.


**Overview of available types**

Type	B32231			
$V_R$ (V DC)	100	250	400	630
$V_{RMS}$ (V AC)	63	160	200	200
$C_R$ ( $\mu$ F)				
0.68				
1.0				
1.5				
2.2				
3.3				
4.7				
10				


**B32231**
**General purpose (wound)**
**Ordering codes and packing units**

$V_R$	$V_{RMS}$ $f \leq 60$ Hz	$C_R$	Max. dimensions $w \times h \times l$	Ordering code (composition see below)	Untaped pcs./MOQ
V DC	V AC	$\mu F$	mm		
100	63	1.0	7.0 × 12.0 × 19.0	B32231D1105+000	4000
		3.3	8.0 × 15.0 × 27.0	B32231D1335+000	4000
		4.7	10.0 × 18.0 × 32.0	B32231D1475+000	2000
		10	13.0 × 23.0 × 32.0	B32231D1106+000	1000
250	160	3.3	10.0 × 18.0 × 32.0	B32231D3335+000	2000
		4.7	13.0 × 20.0 × 32.0	B32231D3475+000	1000
400	200	1.0	9.0 × 16.0 × 27.0	B32231D6105+000	2000
		1.5	10.0 × 18.0 × 32.0	B32231D6155+000	1000
		2.2	13.0 × 22.0 × 32.0	B32231D6225+000	1000
630	200	0.68	10.0 × 16.0 × 32.0	B32231D8684+000	2000
		1.0	13.0 × 18.0 × 32.0	B32231D8105+000	1000

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

**Composition of ordering code**

+ = Capacitance tolerance code:

K =  $\pm 10\%$

J =  $\pm 5\%$  (on request)

**Technical data**

Operating temperature range	Max. operating temperature $T_{op,max}$		+100 °C
	Upper category temperature $T_{max}$		+100 °C
	Lower category temperature $T_{min}$		-40 °C
	Rated temperature $T_R$		+85 °C
Dissipation factor $\tan \delta$ (in $10^{-3}$ ) at 20 °C (upper limit values)	at	$0.10 \mu\text{F} < C_R \leq 1 \mu\text{F}$	$C_R > 1 \mu\text{F}$
	1 kHz	10	10
	10 kHz	25	—
Insulation resistance $R_{ins}$ or time constant $\tau = C_R \cdot R_{ins}$ at 20 °C, rel. humidity $\leq 65\%$ (minimum as-delivered values)	$V_R$	$C_R \leq 0.33 \mu\text{F}$	$C_R > 0.33 \mu\text{F}$
	100 V DC $\geq 250$ V DC	3750 M $\Omega$ 7500 M $\Omega$	1250 s 2500 s
DC test voltage	$1.4 \cdot V_R, 2 \text{ s}$		
Category voltage $V_C$ (continuous operation with $V_{DC}$ or $V_{AC}$ at $f \leq 60$ Hz)	$T_A$ (°C)	DC voltage derating	AC voltage derating
	$T_A \leq 85$ $85 < T_A \leq 100$	$V_C = V_R$ $V_C = V_R \cdot (165 - T_A)/80$	$V_{C,RMS} = V_{RMS}$ $V_{C,RMS} = V_{RMS} \cdot (165 - T_A)/80$
Operating voltage $V_{op}$ for short operating periods ( $V_{DC}$ or $V_{AC}$ at $f \leq 60$ Hz)	$T_A$ (°C)	DC voltage (max. hours)	AC voltage (max. hours)
	$T_A \leq 100$	$V_{op} = 1.25 \cdot V_C$ (2000 h)	$V_{op} = 1.0 \cdot V_{C,RMS}$ (1000 h)
Damp heat test Limit values after damp heat test	21 days/40 °C/93% relative humidity		
	Capacitance change $ \Delta C/C $	$\leq 5\%$	
	Dissipation factor change $\Delta \tan \delta$	$\leq 5 \cdot 10^{-3}$ (at 1 kHz) $\leq 7 \cdot 10^{-3}$ (at 10 kHz)	
	Insulation resistance $R_{ins}$ or time constant $\tau = C_R \cdot R_{ins}$	$\geq 20\%$ of minimum as-delivered values	



**B32231**

**General purpose (wound)**

**Pulse handling capability**

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in V/μs.

"k<sub>0</sub>" represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in V<sup>2</sup>/μs.

*Note:*

*The values of dV/dt and k<sub>0</sub> provided below must not be exceeded in order to avoid damaging the capacitor.*

**dV/dt values**

Length of capacitor		14 mm	19 mm	27 mm	32 mm
V <sub>R</sub> V DC	V <sub>RMS</sub> V AC	dV/dt in V/μs			
100	63	6	3	2	1.5
250	160	10	5	3	2.5
400	200	—	7	4	3
630	200	—	10	7	5

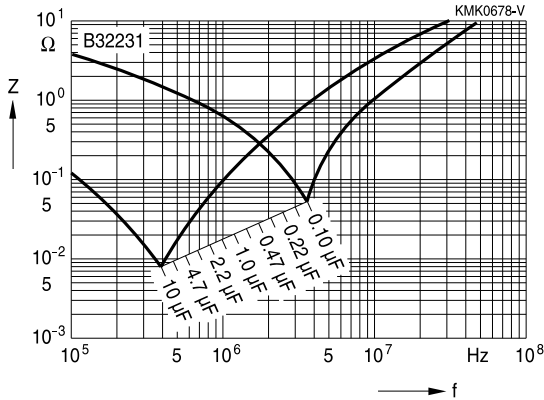
**k<sub>0</sub> values**

Length of capacitor		14 mm	19 mm	27 mm	32 mm
V <sub>R</sub> V DC	V <sub>RMS</sub> V AC	k <sub>0</sub> in V <sup>2</sup> /μs			
100	63	1 200	600	400	300
250	160	5 000	2 500	1 500	1 250
400	200	—	5 600	3 200	2 400
630	200	—	12 500	8 800	6 300



**Impedance Z versus frequency f**

(typical values)



**Permissible AC voltage  $V_{RMS}$  versus frequency**

Values can be obtained on request. In specific cases please provide a scaled voltage/ time graph and state operating conditions.





**B32231**

**General purpose (wound)**

## Mounting guidelines

### 1 Soldering

#### 1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

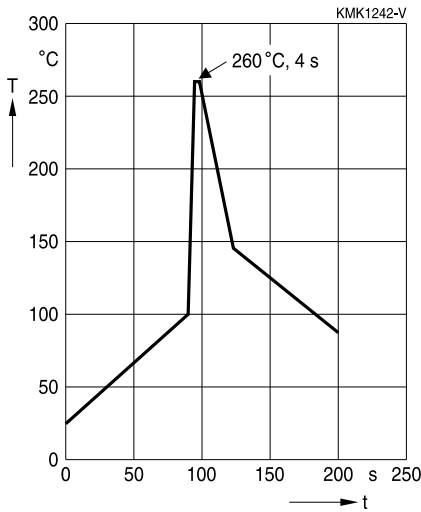
Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria: Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

#### 1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A.

Conditions:

Series	Solder bath temperature	Soldering time
MKT boxed (except 2.5 × 6.5 × 7.2 mm) coated uncoated (lead spacing > 10 mm)	260 ±5 °C	10 ±1 s
MFP MKP (lead spacing > 7.5 mm)		
MKT boxed (case 2.5 × 6.5 × 7.2 mm)		5 ±1 s
MKP (lead spacing ≤ 7.5 mm) MKT uncoated (lead spacing ≤ 10 mm) insulated (B32559)		< 4 s recommended soldering profile for MKT uncoated (lead spacing ≤ 10 mm) and insulated (B32559)



Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
$\tan \delta$	As specified in sectional specification



**B32231**

**General purpose (wound)**

### 1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature  $T_{max}$ . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
  - diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
  - MKP/MFP 110 °C
  - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

#### Uncoated capacitors

For uncoated MKT capacitors with lead spacings  $\leq 10$  mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering



### Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"



**B32231**

**General purpose (wound)**

Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"


**Symbols and terms**

Symbol	English	German
$\alpha$	Heat transfer coefficient	Wärmeübergangszahl
$\alpha_C$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
$\beta_C$	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
C	Capacitance	Kapazität
$C_R$	Rated capacitance	Nennkapazität
$\Delta C$	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
$\Delta t$	Time interval	Zeitintervall
$\Delta T$	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
$\Delta \tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
$\Delta V$	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
$f_1$	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
$f_2$	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
$f_r$	Resonant frequency	Resonanzfrequenz
$F_D$	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
$F_T$	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
$I_C$	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)



**B32231**

**General purpose (wound)**

Symbol	English	German
$I_{RMS}$	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
$i_z$	Capacitance drift	Inkonstanz der Kapazität
$k_0$	Pulse characteristic	Impuls Kennwert
$L_S$	Series inductance	Serieninduktivität
$\lambda$	Failure rate	Ausfallrate
$\lambda_0$	Constant failure rate during useful service life	Konstante Ausfallrate in der Nutzungsphase
$\lambda_{test}$	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
$P_{diss}$	Dissipated power	Abgegebene Verlustleistung
$P_{gen}$	Generated power	Erzeugte Verlustleistung
$Q$	Heat energy	Wärmeenergie
$\rho$	Density of water vapor in air	Dichte von Wasserdampf in Luft
$R$	Universal molar constant for gases	Allg. Molarkonstante für Gas
$R$	Ohmic resistance of discharge circuit	Ohmscher Widerstand des Entladekreises
$R_i$	Internal resistance	Innenwiderstand
$R_{ins}$	Insulation resistance	Isolationswiderstand
$R_P$	Parallel resistance	Parallelwiderstand
$R_S$	Series resistance	Serienwiderstand
$S$	severity (humidity test)	Schärfegrad (Feuchtest)
$t$	Time	Zeit
$T$	Temperature	Temperatur
$\tau$	Time constant	Zeitkonstante
$\tan \delta$	Dissipation factor	Verlustfaktor
$\tan \delta_D$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
$\tan \delta_P$	Parallel component of dissipation factor	Parallelanteil des Verlustfaktors
$\tan \delta_S$	Series component of dissipation factor	Serienanteil des Verlustfaktors
$T_A$	Ambient temperature	Umgebungstemperatur
$T_{max}$	Upper category temperature	Obere Kategorietemperatur
$T_{min}$	Lower category temperature	Untere Kategorietemperatur
$t_{OL}$	Operating life at operating temperature and voltage	Betriebszeit bei Betriebstemperatur und -spannung
$T_{op}$	Operating temperature	Betriebstemperatur
$T_R$	Rated temperature	Nenntemperatur
$T_{ref}$	Reference temperature	Referenztemperatur
$t_{SL}$	Reference service life	Referenz-Lebensdauer
$V_{AC}$	AC voltage	Wechselspannung



Symbol	English	German
$V_C$	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige) Kategorie-Wechselspannung
$V_{CD}$	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
$V_{ch}$	Charging voltage	Ladespannung
$V_{DC}$	DC voltage	Gleichspannung
$V_{FB}$	Fly-back capacitor voltage	Spannung (Flyback)
$V_i$	Input voltage	Eingangsspannung
$V_o$	Output voltage	Ausgangssspannung
$V_{op}$	Operating voltage	Betriebsspannung
$V_p$	Peak pulse voltage	Impuls-Spitzenspannung
$V_{pp}$	Peak-to-peak voltage Impedance	Spannungshub
$V_R$	Rated voltage	Nennspannung
$\hat{V}_R$	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
$V_{RMS}$	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
$V_{SC}$	S-correction voltage	Spannung bei Anwendung "S-correction"
$V_{sn}$	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
$Z$	Impedance	Scheinwiderstand
$e$	Lead spacing	Rastermaß



## Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet ([www.tdk-electronics.tdk.com/material](http://www.tdk-electronics.tdk.com/material)). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order.  
  
We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available. The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.
6. Unless otherwise agreed in individual contracts, **all orders are subject to our General Terms and Conditions of Supply**.
7. **Our manufacturing sites serving the automotive business apply the IATF 16949 standard**. The IATF certifications confirm our compliance with requirements regarding the quality management system in the automotive industry. Referring to customer requirements and customer specific requirements ("CSR") TDK always has and will continue to have the policy of respecting individual agreements. Even if IATF 16949 may appear to support the acceptance of unilateral requirements, we hereby like to emphasize that **only requirements mutually agreed upon can and will be implemented in our Quality Management System**. For clarification purposes we like to point out that obligations from IATF 16949 shall only become legally binding if individually agreed upon.
8. The trade names EPCOS, CeraCharge, CeraDiode, CeraLink, CeraPad, CeraPlas, CSMP, CTVS, DeltaCap, DigiSiMic, ExoCore, FilterCap, FormFit, LeaXield, MiniBlue, MiniCell, MKD, MKK, MotorCap, PCC, PhaseCap, PhaseCube, PhaseMod, PhiCap, PowerHap, PQSine, PQvar, SIFERRIT, SIFI, SIKOREL, SilverCap, SIMDAD, SiMic, SIMID, SineFormer, SIOV, ThermoFuse, WindCap are **trademarks registered or pending** in Europe and in other countries. Further information will be found on the Internet at [www.tdk-electronics.tdk.com/trademarks](http://www.tdk-electronics.tdk.com/trademarks).

Release 2018-10